

## Features

- Single-chip 3.5GHz WiMAX Transceiver
- Fully Differential Design
- Low-IF/Zero-IF Transceiver Architecture; Requires No External Filters
- Self Calibration Mode for RX / TX Filters
- Support Channel Bandwidths of 3.5, 5.0, 7.0, 8.75MHz, and 10MHz
- Modulation up to 64QAM
- Ultra-fast Fractional-N Synthesizer
- Sensitivity < -74 dBm at 64-QAM, CR=3/4, 7MHz BW Typical
- Phase Noise Synthesizer: 0.8° (-37dBc)
- Low Supply Voltage: 3.0 V
- TX Output PRF: 0 dBm, -34 dB EVM
- RX/TX Operating Current: 270/360mA Typical
- 56-lead QFN Package
- Low External Component Count
- Integrated Self IQ Calibration (no external components or control)
- HFDD Support

## Applications

- 3.5 GHz Band Wireless Communication Devices
- IEEE® 802.16-2004 Radios
- Supports OFDM up to 64QAM

## Description

Atmel®'s AT86RF535B is a fully integrated, low cost RF 3.5GHz Low-IF/Zero-IF conversion transceiver for WiMAX applications. It combines excellent RF performance, small size, and low current consumption. The AT86RF535 chip is fabricated on the advanced SiGe BiCMOS process AT46000. The transceiver combines LNA, PA driver, RX/TX mixer, RX/TX filters, VCO, Synthesizer, RX Gain control, and TX Power control, all fully digitally controlled. Only a minimum number of external components are required.



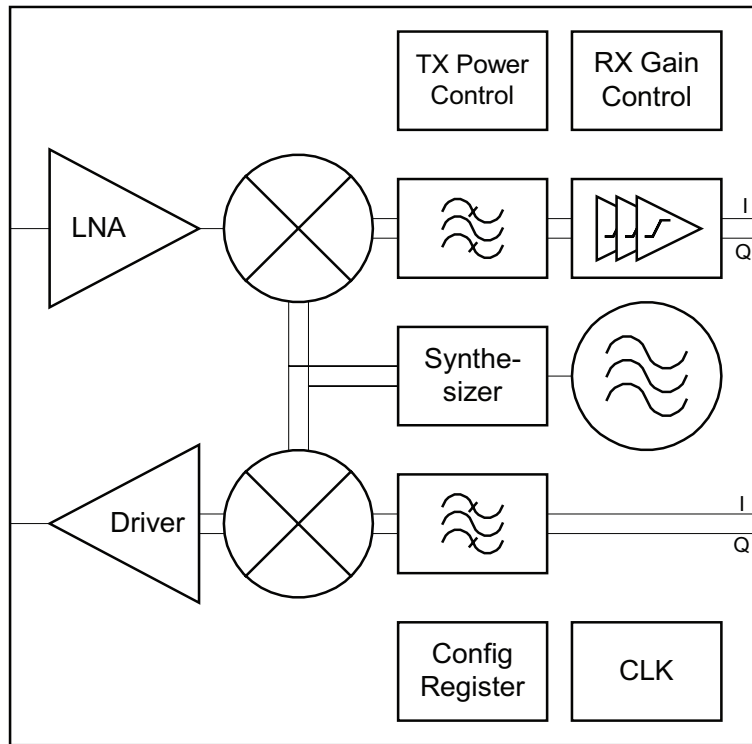
## 3.5GHz WiMAX Transceiver

## AT86RF535B

5190B-WiMAX-9/07



**Figure 1.** AT86RF535B Block Diagram



## Quick Reference Data

**Table 1.** Quick Reference Data

| Symbol      | Parameter                             | Conditions  | Min | Typ        | Max        | Unit    |
|-------------|---------------------------------------|---|-----|------------|------------|---------|
| $F_{RF}$    | Input Center Frequency                |   | 3.4 |            | 3.8        | GHz     |
| DFRS        | Frequency Resolution                  |   |     |            | 19.6       | Hz      |
| $V_{DD}$    | Supply Voltage                        | Applied to VDD pins   | 3.0 | 3.3        | 3.6        | V       |
| $I_{DDRX}$  | Supply Current                        | Receive mode  |     | 270        |            | mA      |
| $I_{DDTX}$  | Supply Current                        | Transmit mode, -5dBm, incl. Balun                           |     | 360        |            | mA      |
| $I_{DDSYN}$ | Supply Current                        | Synthesizer Mode  |     | 135        |            | mA      |
| $I_{DDSTB}$ | Supply Current                        | Stand By Mode,<br>CLK driver activated<br>Clock Load 20pF   |     | 2.5        |            | mA      |
| SENS        | Sensitivity QPSK<br>Sensitivity 64QAM | BW=3.5MHz, CR=1/2, S/N=9.4dB<br>BW=7MHz, CR=3/4, S/N=24.4dB |     | -92<br>-74 | -88<br>-70 | dBm     |
| $P_{RF}$    | TX Output Power                       | FRF= 3.5 GHz, 64QAM, EVM=-34dB, incl. Balun                 |     | 0          |            | dBm     |
| PN          | Integrated Phase Noise of Synthesizer | Integrated over Frequency Range 50kHz ... 1MHz              |     | 0.8        |            | deg rms |
| $T_{AMB}$   | Operating Ambient Temperature         |   | -30 | 27         | +70        | °C      |

Note: All voltages are referred to GND. VDD=3.0V TAMB=27°C, unless otherwise noted.

## Electrical Characteristics

**Table 2.** Receiver Characteristics (Note 1)

| Symbol   | Parameter                             | Conditions  | Min | Typ  | Max        | Unit           |
|--|---------------------------------------|---|-----|------|------------|----------------|
| <b>System</b>  |                                       |   |     |      |            |                |
| $F_{RF}$   | Input Center Frequency                |   | 3.4 |      | 3.8        | GHz            |
| $Z_{IN}$   | Differential Impedance at LNA Input   | Includes a matching inductor and two series capacitors      |     | 100  |            | $\Omega$ diff. |
| SENS   | Sensitivity QPSK<br>Sensitivity 64QAM | BW=3.5MHz, CR=1/2, S/N=9.4dB<br>BW=7MHz, CR=3/4, S/N=24.4dB |     |      | -88<br>-70 | dBm            |
| $P_{IN,MAX}$   | Maximum Input Power                   | BW=7MHz, EVM=24.4dB   | -20 |      |            | dBm            |
| $NF_{SSB}$   | Noise Figure Single Side Band         | high gain mode, includes balun w/o Frontend loss            |     | 5    | 6          | dB             |
| $G_{RX,STEP}$  | RX Chain: Gain Steps                  |   |     | 0.76 |            | dB             |
| $G_{RX,RANGE}$   | RX Chain: Gain Range                  |   |     | 95.5 |            | dB             |
| $t_{RX/TX}$  | RX to TX Switching Time               | TDD Mode<br>HFDD Mode                                       |     |      | 5<br>50    | $\mu$ s        |
| Symbol   | Parameter                             | Conditions  | Min | Typ  | Max        | Unit           |
| <b>System</b>  |                                       |   |     |      |            |                |
| ACR±1  | Adjacent Ch. Rejection                | 16QAM 3/4<br>64QAM 3/4                                      |     |      | -11<br>-4  | dB             |
| ACR±2  | Nonadjacent Ch. Rejection             | 16QAM 3/4<br>64QAM 3/4                                      |     |      | -30<br>-23 | dB             |
| <b>Baseband filters, DC cancellation, RSSI, IQ outputs</b> |                                       |   |     |      |            |                |
| $R_{OUT}$  | Output load resistance                | Pin to GND  | 1   |      |            | M $\Omega$     |
| $C_{OUT}$  | Output load capacitance               | Pin to GND  |     | 20   | 50         | pF             |
| $V_{OMAX}$   | Maximum Output Voltage                | Differential  | 1   |      |            | V              |

|                 |  |  |     |                           |       |             |
|-----------------|--|--|-----|---------------------------|-------|-------------|
| $V_{OUT}$       | I or Q output Voltage                    | Differential at the load specified<br>Output buffer gain offset = +6dB |     | 1                         |       | $V_p, diff$ |
| $G_{B,OFFSTEP}$ | I, Q output buffer:<br>Gain Offset Steps |  |     | 0.76                      |       | dB          |
| $G_{B,RANGE}$   | I, Q output buffer:<br>Gain Range        |  | -9  |                           | +2.25 | dB          |
| $BW_{3dB}$      | 3-dB Bandwidth of Filter                 | 1.875 MHz<br>2.7 MHz<br>3.75 MHz<br>5.0 MHz<br>Note2                   |     | 3.5<br>5.0<br>7.0<br>8.75 |       | MHz         |
| IMRR            | Image Rejection Ratio                    | Note 2   |     | -42                       | -36   | dB          |
| CMD             | Common Mode IQ Voltage                   |  | 1.2 | 1.25                      | 1.35  | V DC        |

**Table 3.** Transmitter Characteristics (Note 1)

| Symbol         | Parameter                               | Conditions  | Min | Typ                       | Max     | Unit            |
|----------------|---|---|-----|---------------------------|---------|-----------------|
| <b>System</b>  |   |   |     |                           |         |                 |
| $F_{RF}$       | Output Center Frequency                 |   | 3.4 |                           | 3.8     | GHz             |
| $Z_{OUT}$      | Differential Impedance at Driver Output |   |     | 100                       |         | $\Omega$ diff   |
| $P_{OUT}$      | TX Output Power                         | For 64QAM modulated signals   |     | 0                         |         | dBm             |
| $t_{TX/RX}$    | TX to RX Switching Time                 | TDD Mode<br>HFDD Mode   |     |                           | 5<br>50 | $\mu$ s         |
| $G_{PA,RANGE}$ | TX Chain Gain Control Range             |   | 50  | 71.9                      |         | dB              |
| $G_{LSB,STEP}$ | TX Chain Gain Control LSB Step Size     |   |     | 0.76                      |         | dB              |
| $BW_{3dB}$     | 3-dB Bandwidth of Filter                | 1.875 MHz<br>2.7 MHz<br>3.75 MHz<br>5.0 MHz<br>Note2                  |     | 3.5<br>5.0<br>7.0<br>8.75 |         | MHz             |
| $L_{Carr}$     | Carrier Leakage                         | Referred to sub carrier level of 64QAM modulated signals<br>Note 2, 3 |     | -20                       | -12     | dBc             |
| IMRR           | Image Rejection Ratio                   | Referred to sub carrier level of 64QAM modulated signals<br>Note 2, 3 |     | -49                       | -45     | dB              |
| EVM            | Error Vector Magnitude                  | 64QAM $\frac{3}{4}$ , 0dBm Output Power                               |     |                           | -34     | dB              |
| $Z_{IN}$       | IQ Input Impedance                      | Differential  |     | 10                        |         | k $\Omega$ diff |
| $V_{IN}$       | IQ Input Voltage                        | Peak, Differential  |     | 1                         |         | $V_p, diff$     |
| $V_{IN,DC}$    | DC Input Voltage                        |   |     | 1.25                      |         | V               |

- Notes: 1. VDD=3.0V, TAMB =27°C, FRF=3.55 GHz, specific application circuit TBD, unless otherwise noted.  
 2. Internally adjusted by build-in self-calibration.  
 3. ETSI Mask Compliant

## Functional Description

The AT86RF535B is based on the IEEE 802.16-2004 standard. This product will provide transmit, receive, and frequency synthesis functions using the OFDM modulation schemes, as defined in the above specifications.

The AT86RF535B consists of a frequency-agile RF transceiver intended for use in 3.5-GHz licensed bands at data rates up to 26Mbps.

Configuration and control registers and a bi-directional data communications interface are available to communicate with existing baseband devices from different vendors. The AT86RF535B addresses the requirements of base station (BS) as well as subscriber stations (SS) equipment. The device will operate down to 3.0V.

The AT86RF535 is fabricated in Atmel's AT46000 advanced SiGe BiCMOS process technology and is assembled in a 8mm x 8mm 56-lead QFN package.

### RX Path

The differential low noise amplifier (DLNA) makes use of a differential bipolar stage with resistive emitter linearization. For digital gain control operation the DLNA supports the four gain modes 0, 6, 12, and 18dB. The linearity improves as the gain is reduced.

The differential inphase quadrature phase mixer (IQMIX) utilizes a differential bipolar stage with emitter degeneration for the best linearity performance. A complex driving LO source is chosen for optimal LO leakage cancellation. The IQMIX has 4, 10, 16, and 22dB of switchable gain.

The receive poly phase filter (RXPPF) is designed as a frequency shifted leapfrog structure. The filter provides three different bandwidths at three different center frequencies. The bandwidth of this filter is tuned by a built-in self-test (BIST). The PPF filter cap values are automatically adjusted upon power-up. The cap tuning can be recalled via SPI. Image rejection is also calibrated upon request via SPI.

There are also three digitally controlled gain amplifiers (DGA1-3) available to provide the necessary amplification for the receive signal. Each stage supports the four gain modes 0, 6, 12, and 18dB, respectively. An additional fine gain stage DGB enables gain tuning of approximately  $\pm 6$ dB in 0.76 dB steps. An output buffer with gain offset matches the voltage swing of the radio to the respective Baseband input stage.

The gain control is complete digital and affects LNA, MIX, and the three DGAs by using the same granularity for each stage. The BB/MAC provides the gain vector at a separated serial interface.

Fast TX/RX switching is possible via TX/RX switch input pins controlled by BB/MAC.

The low-IF conversion receiver does not have to amplify DC signals, but the gain setting process produces different offsets in gain stages. An offset correction takes place after each gain step in the receiver to prevent signal saturation. Every stage has an individual offset correction circuit to maintain the correct overall dynamic range. The DC feedback (DCFB) works as an output offset compensation network, which depends on actual gain setting.

The internal gain control operation is optimized for fixed target amplitude. To adapt to different application requirements, the IQ Output Buffer DGB has a programmable gain offset from  $-1.5$ dB to 6dB in increments of 0.76dB. This allows the nominal output voltage to be set between 180mVp and 650mVp. The gain is controllable via the register setting. The IQOB is able to drive

a capacitive load on all four-output ports (RXI1, RXI2, RXQ1, RXQ2). The CMD pin is available to provide the common mode voltage of the Digital Output Buffer (DGB).

### TX Path

The transmit low pass (TXLP) filter is band limited to meet the emission regulation for OFDM signals. The data signals to the four input ports (TXI1, TXI2, TXQ1, TXQ2) driving the TXLP should be digital but with defined levels.

The complex filtered BB signal is up converted with IQ low-IF up converter (IQUC). A complex driving LO source is used to minimize LO leakage. The output currents of the two mixer stages are added together. The resulting signal drives the power amplifier control block (PAC).

PAC is a Gilbert cell based current domain amplifier with the gain controlled by DC voltage across the mixer core. In that way linear to logarithmic (dB) gain control is achieved.

The BB/MAC provides the gain setting vector at a separated serial interface.

### Synthesizer

The voltage controlled oscillator (VCO) operates at two times the local oscillator (LO) frequency. The VCO output feeds a specialized divide-by-two module. The divider provides the required times one LO frequency with both in-phase and quadrature components for use in the IQ Mixer (IQMIX) and the IQ upconverter (IQUC). The use of the divider at two times the LO also reduces load pull on the LO frequency each time the integrated power amplifier (PA) is enabled.

The VCO core is a differential double-grounded bipolar stage with the load for the VCO tank circuit made up of inductive and capacitive components in parallel. No external tuning devices are required. A fully differential inductor is contained on-chip. The capacitive portion of the frequency determining circuitry is made up of a binary weighted capacitor array and an analog voltage controlled varactor. The radio makes use of a hybrid phase lock loop (PLL) architecture. The coarse tuning is accomplished with the combination of Digital PLL/Binary capacitance array and the fine tuning is accomplished using the more conventional analog portion of the PLL. This use of coarse and fine tuning together reduces the analog VCO gain requirement. The reduction of tuning tolerance issues and noise are a direct effect of this type of PLL. Additionally, the characteristic impedance of the loop filter can be increased to reduce the charge pump current which helps in the integration of the active loop filter on-chip. This PLL also contains both integral and proportional charge pumps whose currents may be changed via register settings. This allows the loop parameters to be optimized for tuning speed and noise reduction.

The fractional-N synthesizer in this radio utilizes a unique phase interpolation divider (PID) rather than the more conventional modulus divider architecture. The PID allows for very good frequency resolution and fast tuning speed. It also has the speed and power advantages of an asynchronous divider and is fully programmable within a restricted frequency range.

Because of the coarse digital tuning the analog tuning gain could be reduced so that the characteristic impedance of the loop filter increases and the charge pump current is reduced. This helps to integrated the whole active loop filter (APLL).

Using of two (proportional and integral components) charge pumps and programming their currents permit changing of filter parameters.

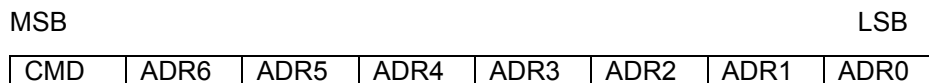
The phase interpolation divider (PDIV) is an alternate divider architecture to a conventional modulus divider. It has the speed and power advantages of an asynchron divider and is programmable in a restricted range.

## Integrated Calibration Support

Calibration of the transceiver imbalances to optimize transmit LO leakage, transmit and receive image rejection ratio (IMRR) will be performed in between RX/TX operation. It is totally independent from BB/MAC processor.

## SPI Interface

Serial peripheral interface (SPI) controls the transceiver. This 4-wire bus contains the ports SDE, SCL, SDI and SDO. The SPI has an 8-bit organization. Each transmission starts with a command byte with the following structure:



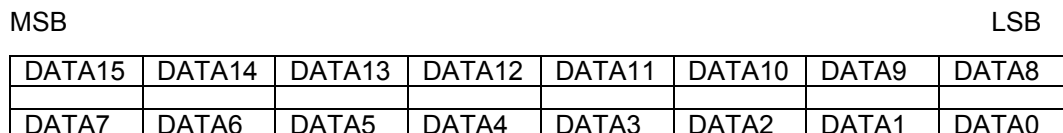
The command bit CMD is set to “1” for WRITE operation and “0” for READ operation.

The transmission is continued with the data bytes. The number of data bytes depends on the register. The MSB of each data byte is send first.

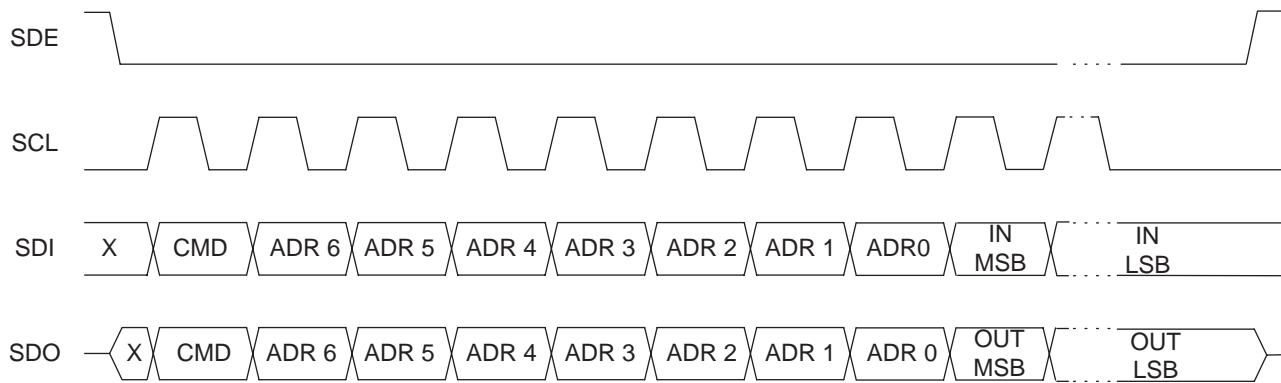
For an 8 bit register:



For a 16 bit register:



**Figure 2.** SPI transmission for multiple bytes



## Pin Description and Package Drawing

**Table 4.** Pin Description

| Pin      | Pin No. | Description  |
|----------|---------|--|
| FSW      | 1       | PLL Frequency Switch for HFDD Mode<br>Digital CMOS input levels  |
| VSSDPLL  | 2       | Ground Supply of Digital PLL Modules   |
| VDDDPLL  | 3       | Voltage Supply of Digital PLL Modules  |
| VDDBBIF  | 4       | Supply Voltage of Digital Base Band Interface Pads   |
| PTX      | 5       | Power Switch Transmit Path<br>High active, digital CMOS input levels   |
| RFRX1    | 6       | RF Receive Input 1<br>Low noise amplifier input. The 50 $\Omega$ matching is in part by the bond/package inductance and an external component (tbd). |
| RFRX2    | 7       | RF Receive Input 2<br>Complementary signal to RFRX1  |
| VSSRFRX  | 8       | Ground Supply of Radio Frequency Receive Circuit Modules   |
| VDDRFRX  | 9       | Voltage Supply of Radio Frequency Receive Circuit Modules  |
| ATB      | 10      | Analog Test Bus Analog IO<br>Analog output/input signal for testing purposes, connection configurable over SPI                                       |
| VDDRFTX1 | 11      | Voltage Supply of Radio Frequency Transmit Circuit Modules   |
| VDDRFTX1 | 12      | Voltage Supply of Radio Frequency Transmit Circuit Module  |
| VDDRFTX2 | 13      | Voltage Supply of Radio Frequency Transmit Circuit Modules   |
| VDDRFTX2 | 14      | Voltage Supply of Radio Frequency Transmit Circuit Modules   |
| VDDPA    | 15      | Voltage Supply of Power Amplifier Driving Module   |
| VDDPA    | 16      | Voltage Supply of Power Amplifier Driving Module   |



**Table 4.** Pin Description (Continued)

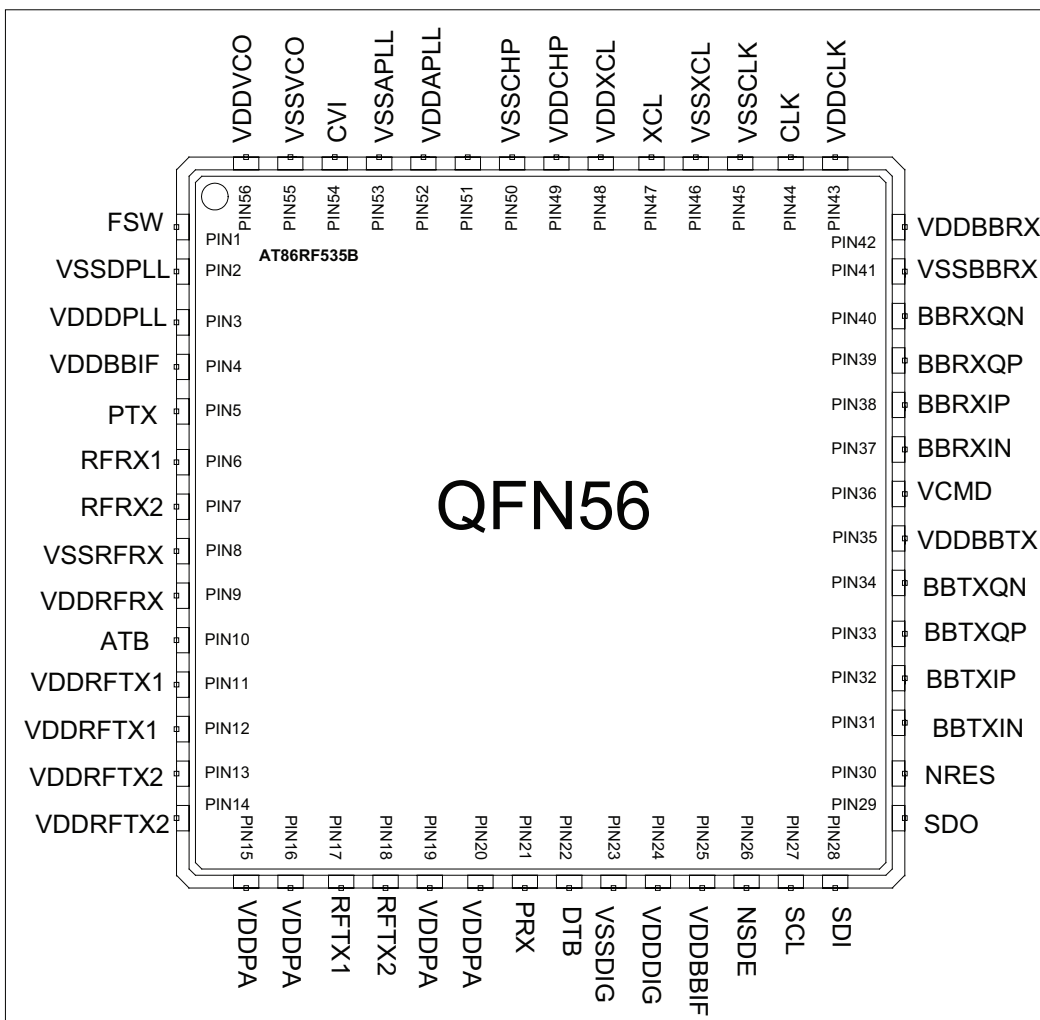
| Pin     | Pin No. | Description  |
|---------|---------|--|
| RFTX1   | 17      | RF Transmit Output 1<br>P1dB up to +15dBm @ 50? differential 3.5GHz. The 50? matching is in part by the bond/package inductance and an external component (tbd).   |
| RFTX2   | 18      | RF Transmit Output 2<br>Complementary signal to RFTX1  |
| VDDPA   | 19      | Voltage Supply of Power Amplifier Driving Module   |
| VDDPA   | 20      | Voltage Supply of Power Amplifier Driving Module   |
| PRX     | 21      | Power Switch of Receive Path<br>High active, digital CMOS input levels   |
| DTB     | 22      | Digital Test Bus Input/Output Digital<br>DTB input/output signal for testing purposes, connection and direction is configurable over SPI.  |
| VSSDIG  | 23      | Ground Supply SPI Interface Pads and of Digital Circuit Modules  |
| VDDDIG  | 24      | Voltage Supply of Digital Circuit Modules  |
| VDDBBIF | 25      | Voltage Supply of Digital Base Band Interface Pads   |
| NSDE    | 26      | SPI Enable Digital Input<br>The rising edge of SCL and a low SDE indicate the start of a data transmission to the SPI slave  |
| SCL     | 27      | SPI Clock Digital Input<br>At every rising edge the SDI data is latched into the internal SPI register. SDO data change also on the rising edge.   |
| SDI     | 28      | SPI Data Digital Input<br>Serial SPI data input stream is started with SDE and contain first an address byte. Read in is MSB first. The MSB of the address byte is the R/W control bit. After the address byte there follows a number of data bytes. The actual number of data bytes depends on the address. |
| SDO     | 29      | SPI Data Digital Output  |
| NRES    | 30      | Power On Reset<br>Low active, open drain output with internal 10k? pull up resistor  |
| BBTXIN  | 31      | Base Band Transmit Input I Negative<br>Complementary signal to BBTXIP  |
| BBTXIP  | 32      | Base Band Transmit Input I Positive<br>Base band transmit input signal In Phase  |
| BBTXQP  | 33      | Base Band Transmit Input Q Positive<br>Complementary signal to BBTXQN  |
| BBTXQN  | 34      | Base Band Transmit Input Q Negative<br>Base band transmit input signal Quad Phase  |
| VDDBBTX | 35      | Voltage Supply of BB TX circuit modules  |
| VCMD    | 36      | Common Mode Voltage Bias Output<br>RX Elements DC output voltage 1.0V, only active if PRX=High   |

**Table 4.** Pin Description (Continued)

| Pin     | Pin No. | Description  |
|---------|---------|--|
| BBRXIN  | 37      | Base Band Receive Output I Negative<br>In Phase output negative. The base band-processed signal is level voltage programmable to adapt to different base band ADCs. The capacitive load should be less than 10pF asymmetric    |
| BBRXIP  | 38      | Base Band Receive Output I Positive<br>Complementary signal to BBRXIN  |
| BBRXQP  | 39      | Base Band Receive Output Q Positive<br>Quad Phase output positive. The base band-processed signal is level voltage programmable to adapt to different base band ADCs. The capacitive load should be less than 10pF asymmetric. |
| BBRXQN  | 40      | Base Band Receive Output Q Negative<br>Complementary signal to BBRXQP  |
| VSSBBRX | 41      | Voltage Supply of BB Receive circuit modules   |
| VDDBBRX | 42      | Voltage Supply of BB Receive circuit modules   |
| VDDCLK  | 43      | Ground Supply of CMOS Clock Output Driver  |
| CLK     | 44      | 40MHz CMOS Clock Digital Output Driver   |
| VSSCLK  | 45      | Ground Supply of CMOS Clock Output Driver  |
| VSSXCL  | 46      | Ground Supply of Crystal Clock Input Buffer  |
| XCL     | 47      | Crystal Clock Input Buffer   |
| VDDXCL  | 48      | Voltage Supply of Crystal Clock Input Buffer   |
| VDDCHP  | 49      | Voltage Supply of Phase Frequency Detector and Charge Pump Modules   |
| VSSCHP  | 50      | Ground Supply of Phase Frequency Detector and Charge Pump Modules  |
|         | 51      |  |
| VDDAPLL | 52      | Voltage Supply of PLL Analog Divider Modules   |
| VSSAPLL | 53      | Ground Supply of PLL Analog Divider Modules  |
| CVI     | 54      | VCO Control Voltage IO (Testpin)   |
| VSSVCO  | 55      | Ground Supply of Synthesizer modules VCO and APLF  |
| VDDVCO  | 56      | Voltage Supply of Synthesizer modules VCO and APLF   |

Note: Additional ground supplies are generated by down bonds to exposed paddle

**Figure 3.** Pin Information



## Revision History

| Doc. Rev. | Date   | Comments   |
|-----------|--------|--|
| 5190B     | 9/2007 | Modified Features<br>Modified data in Quick Reference Data tables<br>Updated to new Template |
| 5190A     | 4/2007 | Initial document release.  |



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